

04-11-2001

Docket No.: END920000040US1

FORM PTO-1595 (Modified)
(Rev. 6-93)
OMB No. 0651-0011 (exp. 4/94)
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3-22-01



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Patent and Trademark Office

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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

David J. Alcoe
Eric A. Johnson
Matthew M. Reiss
Charles G. Woychik

Additional names(s) of conveying party(ies) ☐ Yes ☒ No

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other _____

Execution Date: 3/16/01, 3/16/01, 3/14/01, 3/19/01

2. Name and address of receiving party(ies):

Name: International Business Machines Corporation

Internal Address: _____

Street Address: New Orchard Road

City: Armonk State: NY ZIP: 10504

Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or registration numbers(s):

If this document is being filed together with a new application, the execution date of the application is: 3/16/01, 3/16/01,

A. Patent Application No.(s)

B. Patent No.(s)

3/14/01, 3/19/01

Additional numbers attached? ☐ Yes ☒ No

09/814/789

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Mark Levy

Internal Address: Suite 902

Street Address: SALZMAN & LEVY

19 Chenango St.

City: Binghamton State: NY ZIP: 13901

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.41):.....\$ 40.00

- ☐ Enclosed - Any excess or insufficiency should be credited or debited to deposit account
☒ Authorized to be charged to deposit account

8. Deposit account number:

09-0457

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

LAWRENCE R. FRALEY

Name of Person Signing

Signature

March 21, 2001

Date

Total number of pages including cover sheet, attachments, and document:

3

PATENT

REEL: 011653 FRAME: 0558

IBM Docket No.:
END920000040US1

ASSIGNMENT

Whereas, we

Inventor and City	(1) David J. Alcoe County of Broome	City of Vestal and State of NY
and	(2) Eric A. Johnson County of Chenango	City of Greene and State of NY
and	(3) Matthew M. Reiss County of Broome	City of Endwell and State of NY
and	(4) Charles G. Woychik County of Broome	City of Vestal and State of NY
and	(5) County of	City of and State of
and	(6) County of	City of and State of
and	(7) County of	City of and State of
and	(8) County of	City of and State of

have invented certain improvements in

Title APPARATUS TO REDUCE THERMAL FATIGUE STRESS ON FLIP CHIP SOLDER CONNECTIONS

Dates That
Inventors
Signed the
Declaration

and have executed, respectively, a United States patent application therefor on

(1) 3/16/01	and,	(2) 3/16/01	and,
(3) 3/14/01	and,	(4) 3/19/01	and,
(5) _____	and,	(6) _____	and,
(7) _____	and,	(8) _____	

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we the above named hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

(Signatures of Inventors on Page 2)

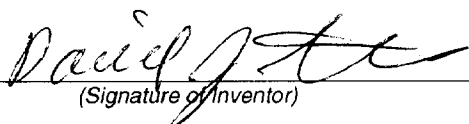
PATENT
REEL: 011653 FRAME: 0559

IBM Docket No.:
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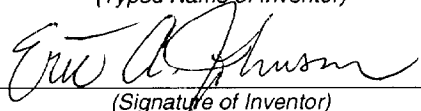
Title APPARATUS TO REDUCE THERMAL FATIGUE STRESS ON FLIP CHIP SOLDER CONNECTIONS

City (1) Signed at Endicott, NY
Date on 3/16/01


(Signature of Inventor)

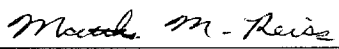
David J. Alcoe
(Typed Name of Inventor)

City (2) Signed at Endicott, NY
Date on 3/16/01


(Signature of Inventor)

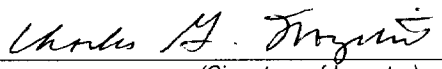
Eric A. Johnson
(Typed Name of Inventor)

City (3) Signed at Endicott, NY
Date on 3/14/01


(Signature of Inventor)

Matthew M. Reiss
(Typed Name of Inventor)

City (4) Signed at Endicott, NY
Date on 3/19/01


(Signature of Inventor)

Charles G. Woychik
(Typed Name of Inventor)

City (5) Signed at
Date on

(Signature of Inventor)

(Typed Name of Inventor)

City (6) Signed at
Date on

(Signature of Inventor)

(Typed Name of Inventor)

City (7) Signed at
Date on

(Signature of Inventor)

(Typed Name of Inventor)

City (8) Signed at
Date on

(Signature of Inventor)

(Typed Name of Inventor)